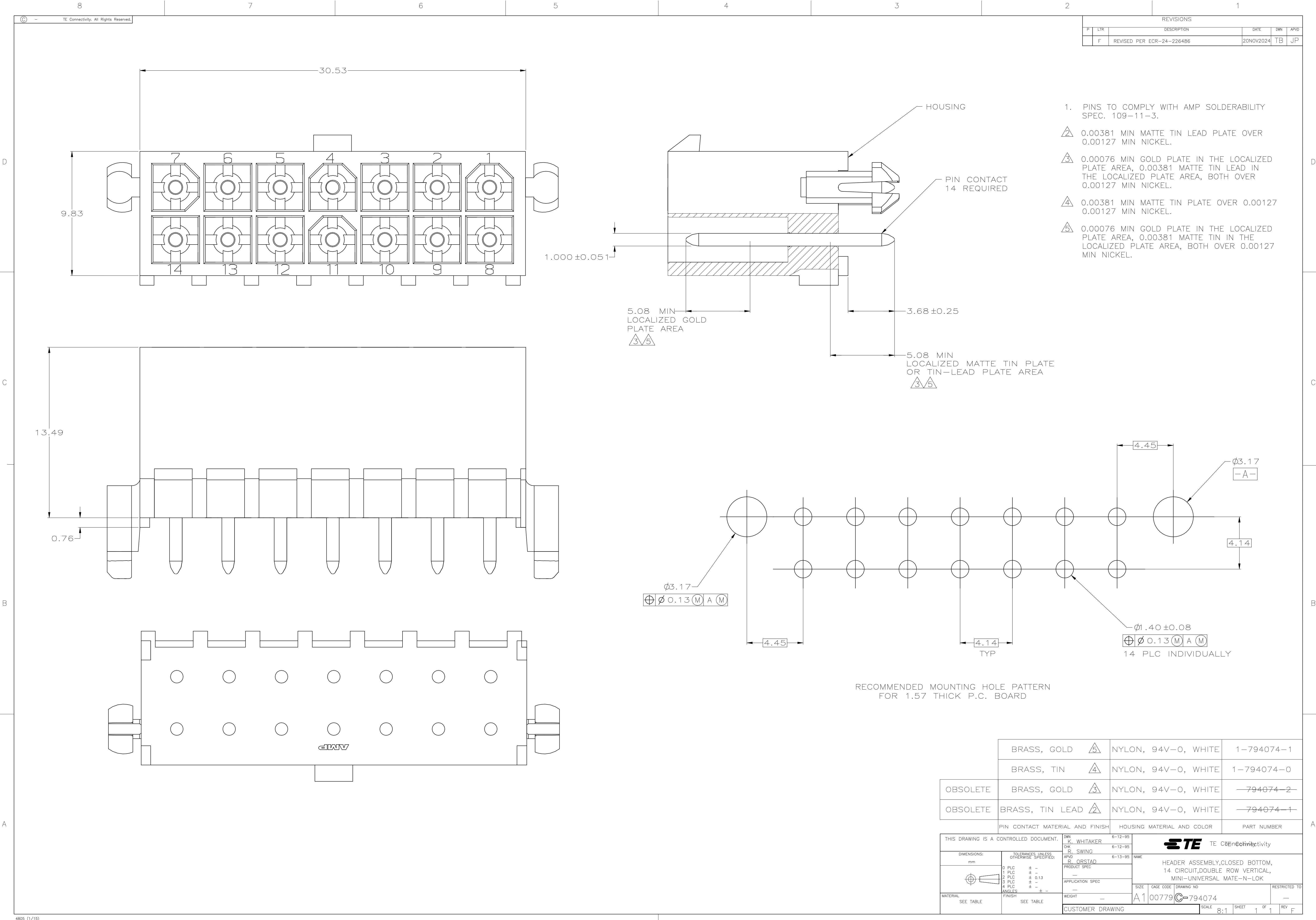




REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
F		REVISED PER ECR-24-226486	20NOV2024	TB	JP

1. PINS TO COMPLY WITH AMP SOLDERABILITY SPEC. 109-11-3.

0.00381 MIN MATTE TIN LEAD PLATE OVER 0.00127 MIN NICKEL.

0.00076 MIN GOLD PLATE IN THE LOCALIZED PLATE AREA, 0.00381 MATTE TIN LEAD IN THE LOCALIZED PLATE AREA, BOTH OVER 0.00127 MIN NICKEL.

0.00381 MIN MATTE TIN PLATE OVER 0.00127 0.00127 MIN NICKEL.

0.00076 MIN GOLD PLATE IN THE LOCALIZED PLATE AREA, 0.00381 MATTE TIN IN THE LOCALIZED PLATE AREA, BOTH OVER 0.00127 MIN NICKEL.

RECOMMENDED MOUNTING HOLE PATTERN FOR 1.57 THICK P.C. BOARD

	BRASS, GOLD	NYLON, 94V-0, WHITE	1-794074-1
	BRASS, TIN	NYLON, 94V-0, WHITE	1-794074-0
OBSOLETE	BRASS, GOLD	NYLON, 94V-0, WHITE	794074-2
OBSOLETE	BRASS, TIN LEAD	NYLON, 94V-0, WHITE	794074-1
PIN CONTACT MATERIAL AND FINISH		HOUSING MATERIAL AND COLOR	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT.		TE Connectivity	
DIMENSIONS: mm		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC	
0. PLC ± -		APPLICATION SPEC	
1. PLC ± 0.13		WEIGHT	
2. PLC ± 0.13		CUSTOMER DRAWING	
3. PLC ± -		SCALE 8:1	
4. PLC ± -		SHEET 1 OF 1	
ANGLES ± -		REV F	
FINISH SEE TABLE		RESTRICTED TO	